

WEST

Generate Collection

Print

Search Results - Record(s) 1 through 2 of 2 returned.☐ 1. Document ID: JP 2000016821 A

L1: Entry 1 of 2

File: JPAB

Jan 18, 2000

PUB-NO: JP02000016821A

DOCUMENT-IDENTIFIER: JP 2000016821 A

TITLE: PRODUCTION OF JIG FOR PROCESSING SEMICONDUCTOR WAFER AND JIG

PUBN-DATE: January 18, 2000

INVENTOR-INFORMATION:

NAME

COUNTRY

MATSUDA, TAKASHI

KONDO, KAZUSADA

ABE, EMIKO

ASSIGNEE-INFORMATION:

NAME

COUNTRY

NIPPON SILICA GLASS CO LTD

APPL-NO: JP10188409

APPL-DATE: July 3, 1998

INT-CL (IPC): C03 B 20/00; B08 B 3/08; B08 B 3/10; H01 L 21/304; H01 L 21/68

ABSTRACT:

PROBLEM TO BE SOLVED: To produce a jig for the processing of a semiconductor wafer and made of a quartz glass having high etching resistance, causing little generation of dust such as particles and effective for stabilizing the surface treatment of the jig as a post-treatment process by completely removing stains such as oil attached to a quartz glass jig for the processing of a semiconductor.

SOLUTION: A grooved rod for supporting a wafer boat and having a groove formed by grinding with a diamond wheel is washed with shower of a surfactant having a concentration of 0.5-5 wt.% to remove the oil and fat component remaining on the surface of the quartz glass. The substrate is subsequently subjected to deep etching surface-treatment with 15% HF (hydrofluoric acid). A clean quartz glass jig for the processing of a semiconductor, having smooth surface and causing little generation of dust can be produced by heating the groove with an automatic groove heating apparatus before the surface-treatment.

COPYRIGHT: (C)2000,JPO

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWC
Draw	Desc	Image									

☐ 2. Document ID: JP 2000016821 A

L1: Entry 2 of 2

File: DWPI

Jan 18, 2000